

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo





FDA15N65

650V N-Channel MOSFET

Features

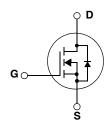
- 16A, 650V, $R_{DS(on)} = 0.44\Omega @V_{GS} = 10 V$
- Low gate charge (typical 48.5 nC)
- Low C_{rss} (typical 23.6 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability

Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.





Absolute Maximum Ratings

| Symbol | | Parameter | | FDA15N65 | Unit |
|----------------------------------|--|--|-------------|-----------|--------|
| V _{DSS} | Drain-Source Voltage | | | 650 | V |
| I _D | Drain Current | - Continuous (T _C = 25°C) - Continuous (T _C = 100°C |) | 16 9.6 | A A |
| I _{DM} | Drain Current | - Pulsed | (Note 1) | 64 | A |
| V _{GSS} | Gate-Source voltage | | ± 30 | V | |
| E _{AS} | Single Pulsed Avalanche Energy (Note 2) | | 637 | mJ | |
| I _{AR} | Avalanche Current | | (Note 1) | 16 | A |
| E _{AR} | Repetitive Avalanche | Energy | (Note 1) | 26 | mJ |
| dv/dt | Peak Diode Recovery | / dv/dt | (Note 3) | 4.5 | V/ns |
| P _D | Power Dissipation (T _C = 25°C) - Derate above 25°C | | 260 2.1 | W/°C | |
| T _{J,} T _{STG} | Operating and Storage Temperature Range | | -55 to +150 | °C | |
| T _L | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | | 300 | °C | |

Thermal Characteristics

| Symbol | Parameter | Min. | Max. | Unit |
|-----------------|---|------|------|------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | | 0.48 | °C/W |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink | 0.24 | | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | | 40 | °C/W |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|-----------------------|----------|---------|-----------|------------|----------|
| FDA15N65 | FDA15N65 | TO-3PN | | | 30 |

Electrical Characteristics T_C = 25°C unless otherwise noted

| Symbol | Parameter | Conditions | Min | Тур | Max | Units | |
|--|--|--|-----|------|---------|----------|--|
| Off Charac | Off Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0V$, $I_D = 250\mu A$, $T_J = 25^{\circ}C$ | 650 | | | V | |
| ΔBV _{DSS} / ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 250μA, Referenced to 25°C | | 0.65 | | V/°C | |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 650V, V _{GS} = 0V V _{DS} = 520V, T _C = 125°C | | | 1 10 | μA μA | |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30V, V _{DS} = 0V | | | 100 | nA | |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = -30V, V _{DS} = 0V | | | -100 | nA | |
| On Charac | teristics | | | • | | • | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | 3.0 | | 5.0 | V | |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10V, I _D = 8A | | 0.36 | 0.44 | Ω | |
| g _{FS} | Forward Transconductance | V _{DS} = 40V, I _D = 8A (Note 4) | | 19.2 | | S | |
| Dynamic C | Characteristics | | | | | • | |
| C _{iss} | Input Capacitance | $V_{DS} = 25V, V_{GS} = 0V,$ | | 2380 | 3095 | pF | |
| C _{oss} | Output Capacitance | f = 1.0MHz | | 295 | 385 | pF | |
| C _{rss} | Reverse Transfer Capacitance |] | | 23.6 | 35.5 | pF | |
| Switching | Characteristics | | | | • | | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} = 325V, I _D = 15A | | 65 | 140 | ns | |
| t _r | Turn-On Rise Time | $R_G = 21.7\Omega$ | | 125 | 260 | ns | |
| t _{d(off)} | Turn-Off Delay Time |] | | 105 | 220 | ns | |
| t _f | Turn-Off Fall Time | (Note 4, 5) | | 65 | 140 | ns | |
| Q _g | Total Gate Charge | V _{DS} = 520V, I _D = 15A | | 48.5 | 63.0 | nC | |
| Q _{gs} | Gate-Source Charge | V _{GS} = 10V | | 14.0 | | nC | |
| Q _{gd} | Gate-Drain Charge | (Note 4, 5) | | 21.2 | | nC | |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | | |
| I _S | I _S Maximum Continuous Drain-Source Diode Forward Current | | | | 16 | Α | |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current | | | | 64 | Α | |
| V _{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0V, I _S = 16A | | | 1.4 | V | |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0V, I _S = 15A | | 496 | | ns | |
| Q _{rr} | Reverse Recovery Charge | $dI_F/dt = 100A/\mu s $ (Note 4) | | 5.69 | | μС | |

NOTES

^{1.} Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} L = 4.6mH, I_{AS} = 16A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C

^{3.} $I_{SD} \leq$ 16A, di/dt \leq 200A/ μ s, $V_{DD} \leq$ BV $_{DSS}$, Starting T_J = 25°C

^{4.} Pulse Test: Pulse width $\leq 300 \mu s,$ Duty Cycle $\leq 2\%$

^{5.} Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

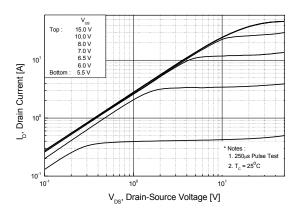


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

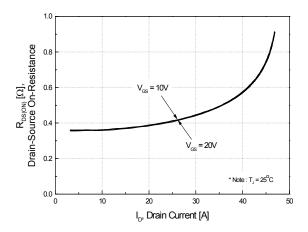


Figure 5. Capacitance Characteristics

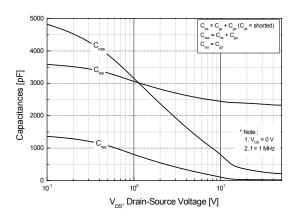


Figure 2. Transfer Characteristics

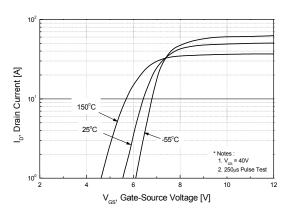


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

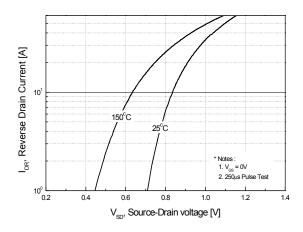
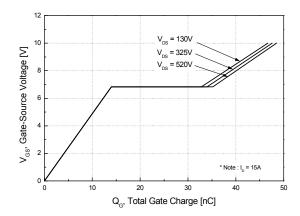


Figure 6. Gate Charge Characteristics



3

Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

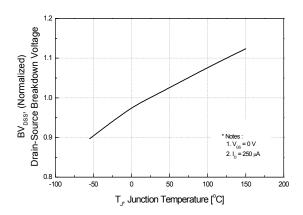


Figure 8. On-Resistance Variation vs. Temperature

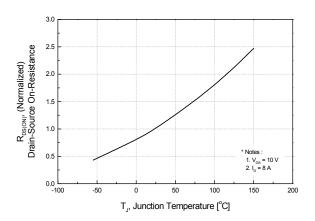


Figure 9. Safe Operating Area

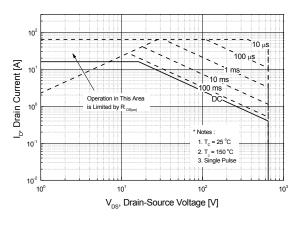


Figure 10. Maximum Drain Current vs. Case Temperature

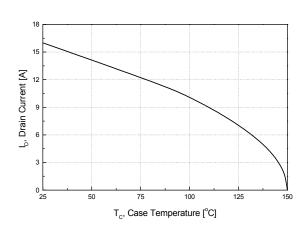
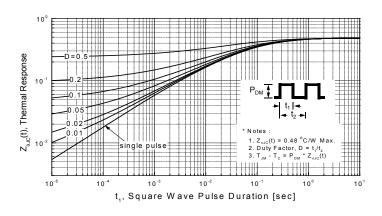
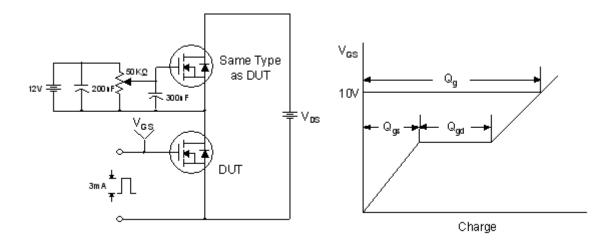


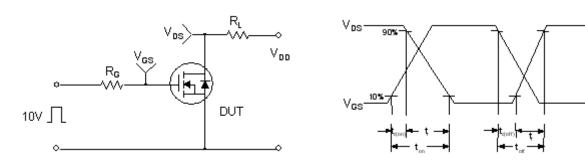
Figure 11. Transient Thermal Response Curve



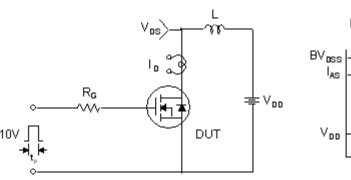
Gate Charge Test Circuit & Waveform

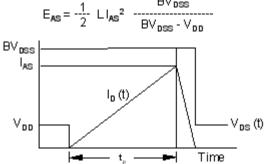


Resistive Switching Test Circuit & Waveforms

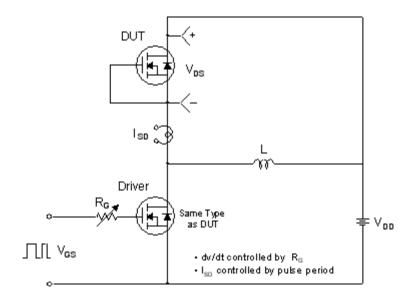


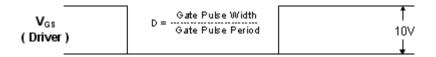
Unclamped Inductive Switching Test Circuit & Waveforms

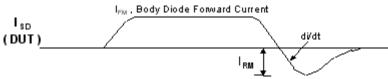




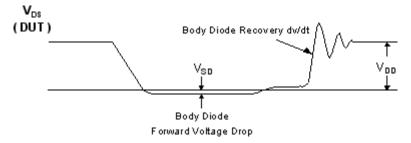
Peak Diode Recovery dv/dt Test Circuit & Waveforms





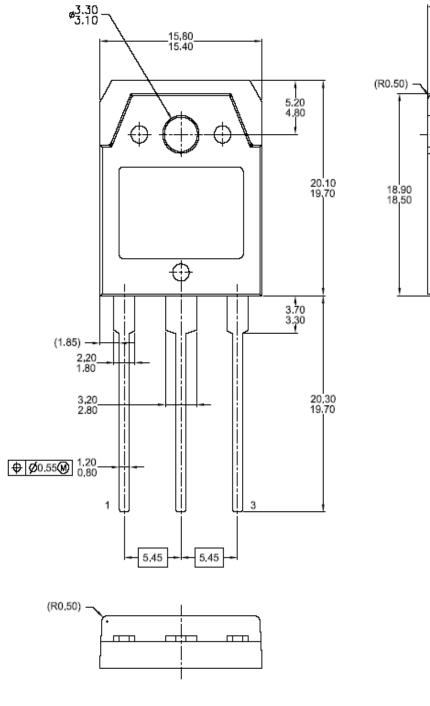


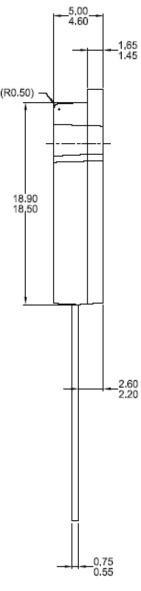
Body Diode Reverse Current



Mechanical Dimensions

TO-3PN





Dimensions in Millimeters

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

| ACEx™ | FACT Quiet Series™ | OCX™ | SILENT SWITCHER® |
|-------------------------|---------------------|--------------------------|------------------------|
| ActiveArray™ | GlobalOptoisolator™ | OCXPro™ | SMART START™ |
| Bottomless™ | GTO™ | OPTOLOGIC® | SPM™ |
| Build it Now™ | HiSeC™ | OPTOPLANAR™ | Stealth™ |
| CoolFET™ | I ² C™ | PACMAN™ | SuperFET™ |
| CROSSVOLT™ | i-Lo™ | POP™ | SuperSOT™-3 |
| DOME™ | ImpliedDisconnect™ | Power247™ | SuperSOT™-6 |
| EcoSPARK™ | IntelliMAX™ | PowerEdge™ | SuperSOT™-8 |
| E ² CMOS™ | ISOPLANAR™ | PowerSaver™ | SyncFET™ |
| EnSigna™ | LittleFET™ | PowerTrench [®] | TCM™ |
| FACT [®] | MICROCOUPLER™ | QFET [®] | TinyBoost™ |
| FAST [®] | MicroFET™ | QS™ | TinyBuck™ |
| FASTr™ | MicroPak™ | QT Optoelectronics™ | TinyPWM™ |
| FPS™ | MICROWIRE™ | Quiet Series™ | TinyPower™ |
| FRFET™ | MSX™ | RapidConfigure™ | TinyLogic [®] |
| | MSXPro™ | RapidConnect™ | TINYOPTO™ |
| Across the board. Aroun | d the world.™ | µSerDes™ | TruTranslation™ |
| The Power Franchise® | | ScalarPump™ | UHC® |

The Power Franchise® ScalarPump™

Programmable Active Droop™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

UniFET™ VCX™ Wire™

PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|------------------------|---|
| Advance Information | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| No Identification Needed | Full Production | This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. |
| Obsolete | Not In Production | This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only. |

Rev. 122

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor nessure any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, a

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative